IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfc Information				
upplier Inform	nation								·					
ompany name*		Company unique ID			Ur	Unique ID Authority				Response Date*				
nsemi										2023-06-08				
Contact Name		Title - Contact			Ph	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Ph	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			N	NA NA				Product-Env-Stewards@onsemi.com			
Request	er Item Number			mber Mfr Item Name		E	Effective Date	Version	on Manufacturing Site		1	Weight*	UOM	Unit Type
				42V 8A Fully Prote	otected Low Side Driver		2023-06-08				350.99	mg	Each	
	Process Information			A11	CTD 020 MCI Dat		Deels Dees	D. d. T		Mary Times at Basil	T	Name h		1
		,		STD-020 MSL Rati	ıng	Peak Process Body Te		emperatui				er of Reflow Cyc	cies	
•	in (Sn) - annealed	C	U Alloy	1			260		IC	30	secon	ds   3		
omments														
	time at peak temperature													
or more informat	ion regarding material co	omposition p	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	A	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Epoxy resin	proprietary data		9.0755	mg
			Supplier	Phenolic Resin	Proprietary Data		3.8895	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		12.965	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		103.0717	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	1.37	mg	Supplier	Aluminum (Al)	7429-90-5		1.37	mg